

WHAT IS CLAIMED IS:

1. A die bonder which mounts on a base piece by piece, the dies each having a surface on which a semiconductor device is formed, the die bonder comprising:
a laser machining part which causes laser light to become incident from a surface of a wafer before dividing into individual dies so that the laser light forms a modified region within the wafer,
wherein the wafer is divided into individual dies in the laser machining part.
2. The die bonder as defined in claim 1, wherein a product type marking is provided on a surface of the die by the laser machining part.
3. The die bonder as defined in claim 1, wherein all dies on the wafer are divided into the individual dies by the laser machining part.
4. The die bonder as defined in claim 3, wherein a product type marking is provided on a surface of the die by the laser machining part.
5. The die bonder as defined in claim 1, wherein only conforming dies on the wafer are divided into the individual dies by the laser machining part.
6. The die bonder as defined in claim 5, wherein a product type marking is provided on a surface of the die by the laser machining part.